

# 3A, 400V - 600V High Efficient Surface Mount Rectifier

#### **FEATURES**

- Glass passivated chip junction
- Ideal for automated placement
- Fast switching for high efficiency
- Moisture sensitivity level: level 1, per J-STD-020
- RoHS Compliant
- Halogen-free according to IEC 61249-2-21

#### **APPLICATIONS**

- Switching mode power supply (SMPS)
- Adapters
- Monitor
- TV

#### **MECHANICAL DATA**

- Case: DO-214AA (SMB)
- Molding compound meets UL 94V-0 flammability rating
- Terminal: Matte tin plated leads, solderable per J-STD-002
- Meet JESD 201 class 2 whisker test
- · Polarity: Indicated by cathode band
- Weight: 0.110g (approximately)

KEY PARAMETERS			
PARAMETER	VALUE	UNIT	
I <sub>F</sub>	3	Α	
$V_{RRM}$	400 - 600	<b>V</b>	
I <sub>FSM</sub>	75	Α	
T <sub>J MAX</sub>	175	°C	
Package	DO-214AA (SMB)		
Configuration	Single die		













ABSOLUTE MAXIMUM RATINGS (T <sub>A</sub> = 25°C unless otherwise noted)				
PARAMETER	SYMBOL	MUR340SB	MUR360SB	UNIT
Marking code on the device		MUR340SB	MUR360SB	
Repetitive peak reverse voltage	$V_{RRM}$	400	600	V
Reverse voltage, total rms value	$V_{R(RMS)}$	280	420	V
Forward current	I <sub>F</sub>	3		Α
Surge peak forward current, 8.3ms single half sine-wave superimposed on rated load	I <sub>FSM</sub>	75		А
Junction temperature	T <sub>J</sub>	- 55 to +175		°C
Storage temperature	T <sub>STG</sub>	- 55 to +175		°C

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THERMAL PERFORMANCE			
PARAMETER	SYMBOL	TYP	UNIT
Junction-to-lead thermal resistance	R <sub>OJL</sub>	11	°C/W
Junction-to-ambient thermal resistance	R <sub>OJA</sub>	57	°C/W
Junction-to-case thermal resistance	R <sub>eJC</sub>	14	°C/W

Thermal Performance Note: Units mounted on PCB (10mm x 10mm Cu pad test board)

ELECTRICAL SPECIFICATIONS (T <sub>A</sub> = 25°C unless otherwise noted)					
PARAMETER	CONDITIONS	SYMBOL	TYP	MAX	UNIT
Forward voltage <sup>(1)</sup>	I <sub>F</sub> = 1.5A, T <sub>J</sub> = 25°C	V <sub>F</sub>	1.00	1.10	V
	$I_F = 3.0A, T_J = 25^{\circ}C$		1.10	1.25	V
	I <sub>F</sub> = 1.5A, T <sub>J</sub> = 150°C		0.76	1.00	V
	$I_F = 3.0A, T_J = 150^{\circ}C$		0.89	1.05	V
Reverse current @ rated V <sub>R</sub> <sup>(2)</sup>	T <sub>J</sub> = 25°C	I <sub>R</sub>	-	10	μΑ
	T <sub>J</sub> = 150°C		-	250	μA
Junction capacitance	1MHz, $V_R = 4.0V$	CJ	38	-	pF
Reverse recovery time	$I_F = 0.5A$ , $I_R = 1.0A$ , $I_{rr} = 0.25A$	t <sub>rr</sub>	-	50	ns

## Notes:

- 1. Pulse test with PW = 0.3ms
- 2. Pulse test with PW = 30ms

ORDERING INFORMATION			
ORDERING CODE <sup>(1)</sup>	PACKAGE	PACKING	
MUR3xSB	DO-214AA (SMB)	3,000 / Tape & Reel	

## Notes:

1. "x" defines voltage from 400V(MUR340SB) to 600V(MUR360SB)



## **CHARACTERISTICS CURVES**

 $(T_A = 25^{\circ}C \text{ unless otherwise noted})$ 

**Fig.1 Forward Current Derating Curve** 

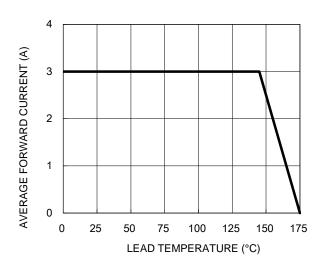


Fig.3 Typical Reverse Characteristics

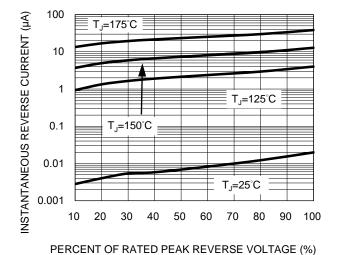
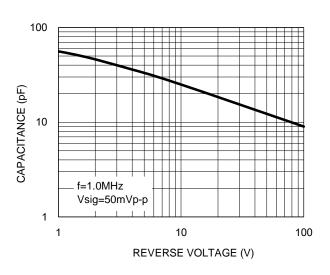
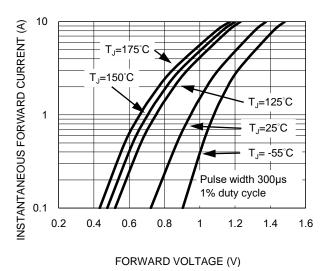


Fig.2 Typical Junction Capacitance



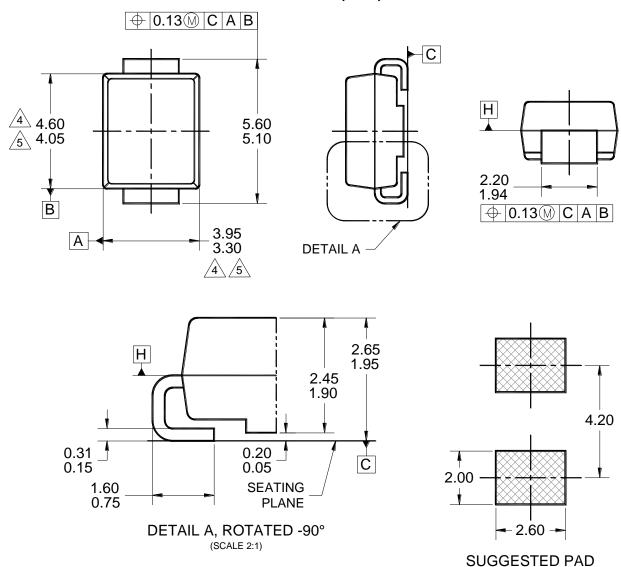
**Fig.4 Typical Forward Characteristics** 

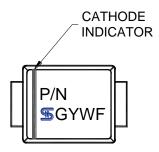




# **PACKAGE OUTLINE DIMENSIONS**

## **DO-214AA (SMB)**





#### MARKING DIAGRAM

P/N = MARKING CODE

G = GREEN COMPOUND

YW = DATE CODE

F = FACTORY CODE

#### NOTES: UNLESS OTHERWISE SPECIFIED

1. ALL DIMENSIONS ARE IN MILLIMETERS.

**LAYOUT** 

- 2. DIMENSIONING AND TOLERANCING PER ASME Y14.5M-1994.
- 3. PACKAGE OUTLINE REFERENCE: JEDEC DO-214, VARIATION AA, ISSUE D.
- MOLDED PLASTIC BODY DIMENSIONS DO NOT INCLUDE MOLD FLASH.
- MOLDED PLASTIC BODY LATERAL DIMENSIONS TO BE DETERMINED AT DATUM PLANE H.
- 6. DWG NO. REF: HQ2SD07-DO214SMB-035 REV A.



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